

# MJ N-Channel Enhancement Mode Power MOSFET

## Description

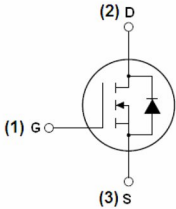
The MJ0157T uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### General Features

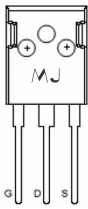
- ◆  $V_{DS}=100V, I_D=57A$   
 $R_{DS(ON)}<16m\Omega$  @  $V_{GS}=10V$  (Typ11.7m $\Omega$ )
- ◆ Special process technology for high ESD capability
- ◆ High density cell design for ultra low  $R_{dson}$
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high  $E_{AS}$
- ◆ Excellent package for good heat dissipation

### Application

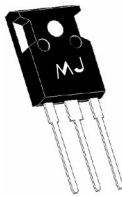
- ◆ Power switching application
- ◆ Hard Switched and High Frequency Circuits
- ◆ Uninterruptible Power Supply



Schematic diagram



Marking and pin assignment



TO-247 top view

100% UIS TESTED! 100%  $\Delta V_{ds}$  TESTED!

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ0157T	MJ0157T	TO-247	-	-	-

### Absolute Maximum Ratings (T<sub>c</sub> =25 °C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	±20	V
Drain Current-Continuous	$I_D$	57	A
Drain Current-Continuous(T <sub>c</sub> =100°C)	$I_{D(100^{\circ}C)}$	40	A
Pulsed Drain Current	$I_{DM}$	190	A
Maximum Power Dissipation	$P_D$	180	W
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	580	mJ
Derating factor		1.2	W/°C
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	°C

### Thermal Characteristic

Thermal Resistance,Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JA}$	0.83	°C/W
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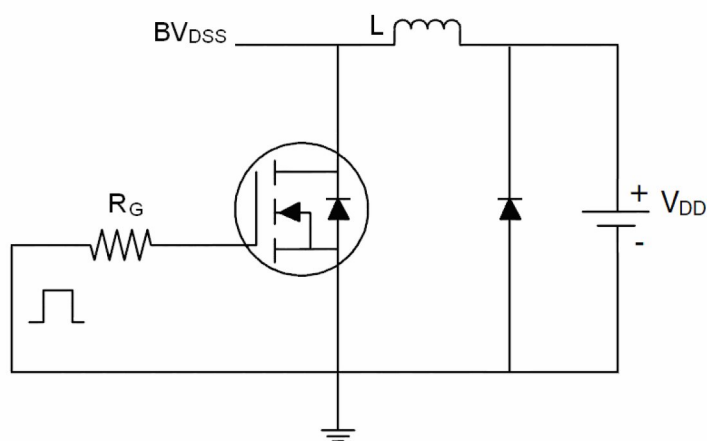
Electrical Characteristics (T<sub>A</sub> =25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	100	110	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics <sup>(Note 3)</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	2	3	4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =28A	-	11.7	16	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =25V,I <sub>D</sub> =28A	32	-	-	S
Dynamic Characteristics <sup>(Note 4)</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V, F=1.0MHz	-	4400	-	PF
Output Capacitance	C <sub>oss</sub>		-	320	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	240	-	PF
Switching Characteristics <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =50V,I <sub>D</sub> =28A V <sub>GS</sub> =10V,R <sub>GEN</sub> =2.5Ω	-	12	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	55	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	45	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	47	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =80V,I <sub>D</sub> =28A, V <sub>GS</sub> =10V	-	95	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	18	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	25	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =28A	-	0.85	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	I <sub>S</sub>		-	-	57	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> =25°C, I <sub>F</sub> =28A di/dt=100A/μs <sup>(Note 3)</sup>	-	36	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	56	-	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is negligible(turn-on is dominated by LS+LD)				

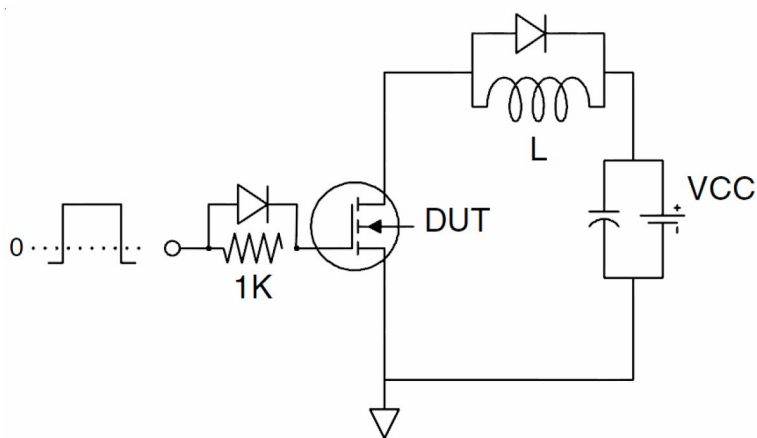
## Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- ④ Guaranteed by design, not subject to production
- ⑤ EAS condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, L=0.5mH, R<sub>g</sub>=25Ω

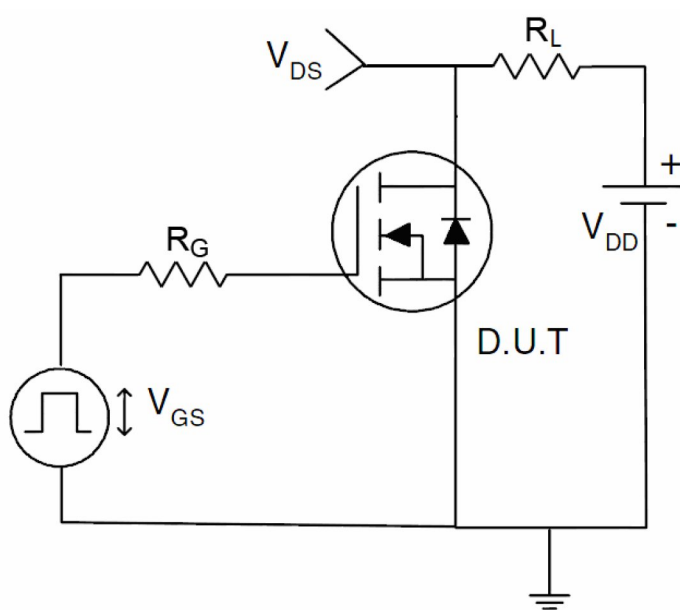
## Test circuit



EAS test Circuit

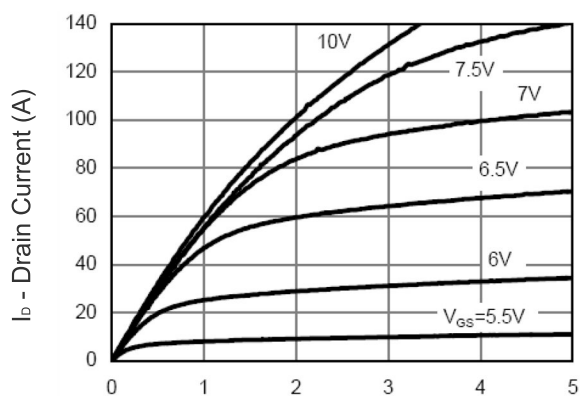


Gate charge test Circuit



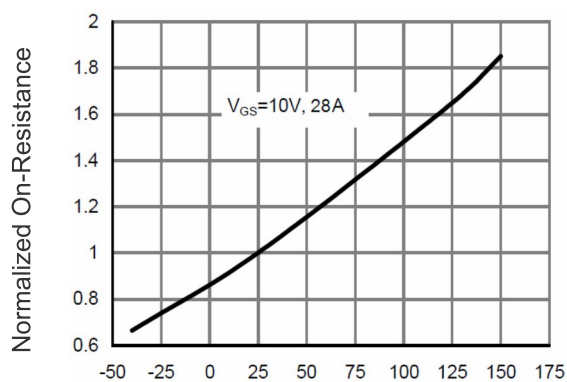
Switch Time Test Circuit

# Typical Electrical and Thermal Characteristics (Curves)



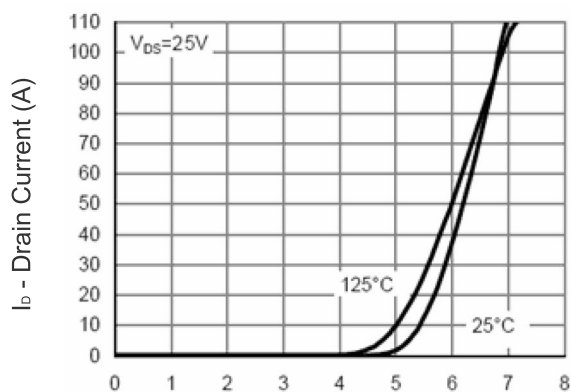
Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



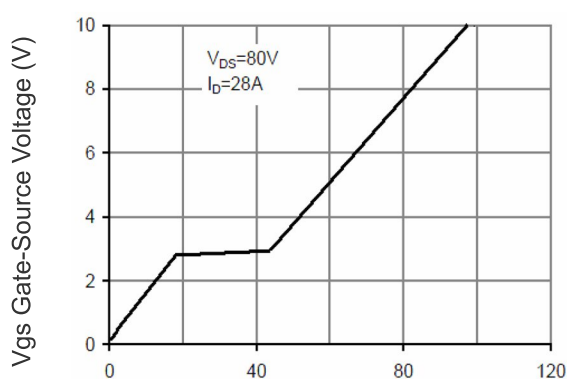
Tj -Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



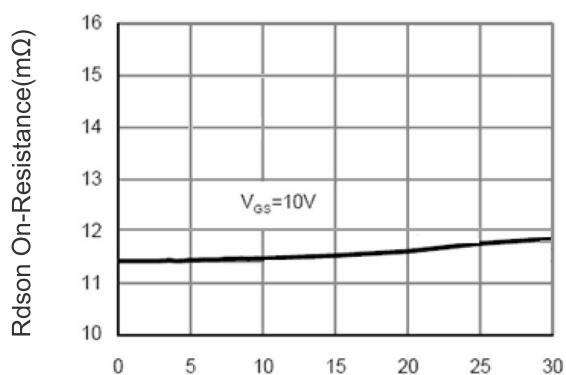
Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



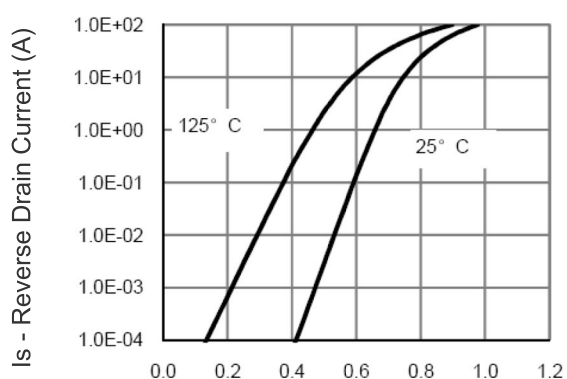
Qg Gate Charge (nC)

Figure 5 Gate Charge



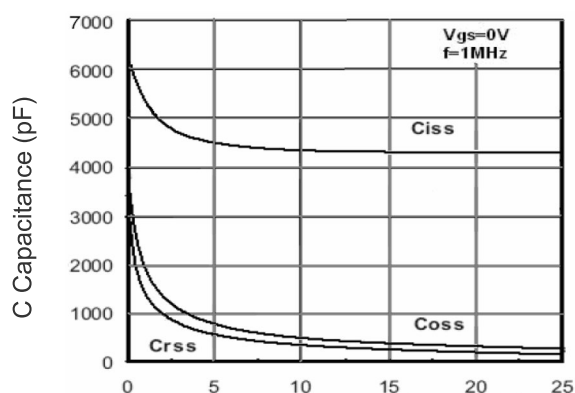
Id - Drain Current (A)

Figure 3 Rdson- Drain Current



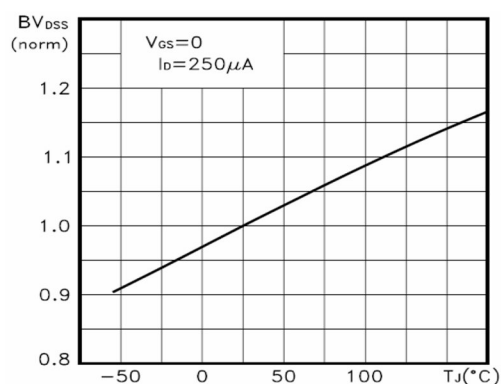
Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward



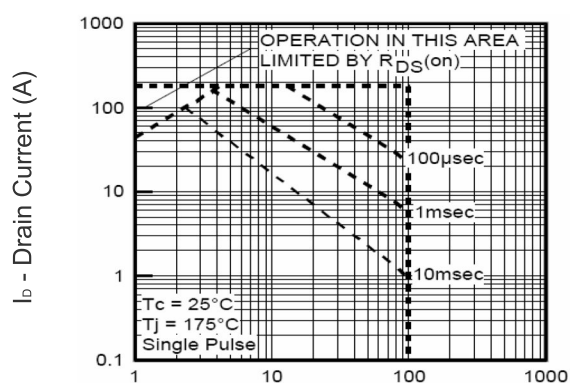
V<sub>ds</sub> Drain-Source Voltage (V)

Figure 7 Capacitance vs V<sub>ds</sub>



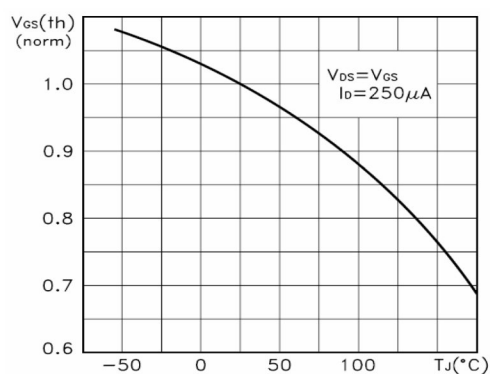
T<sub>J</sub> -Junction Temperature(°C)

Figure 9 BV<sub>DSS</sub> vs Junction Temperature



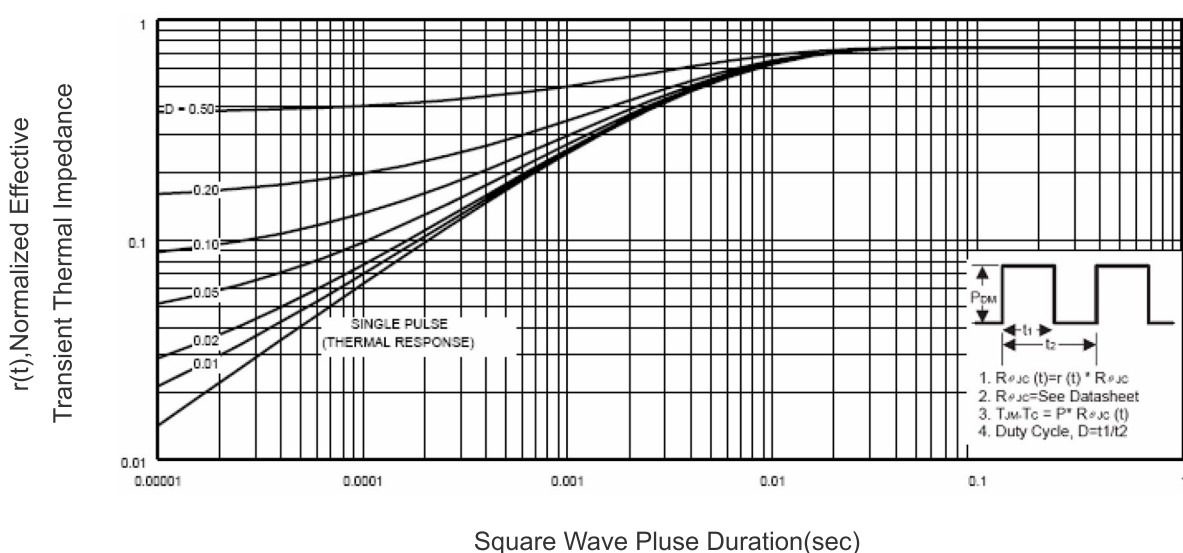
V<sub>ds</sub> Drain-Source Voltage (V)

Figure 8 Safe Operation Area



T<sub>J</sub> -Junction Temperature(°C)

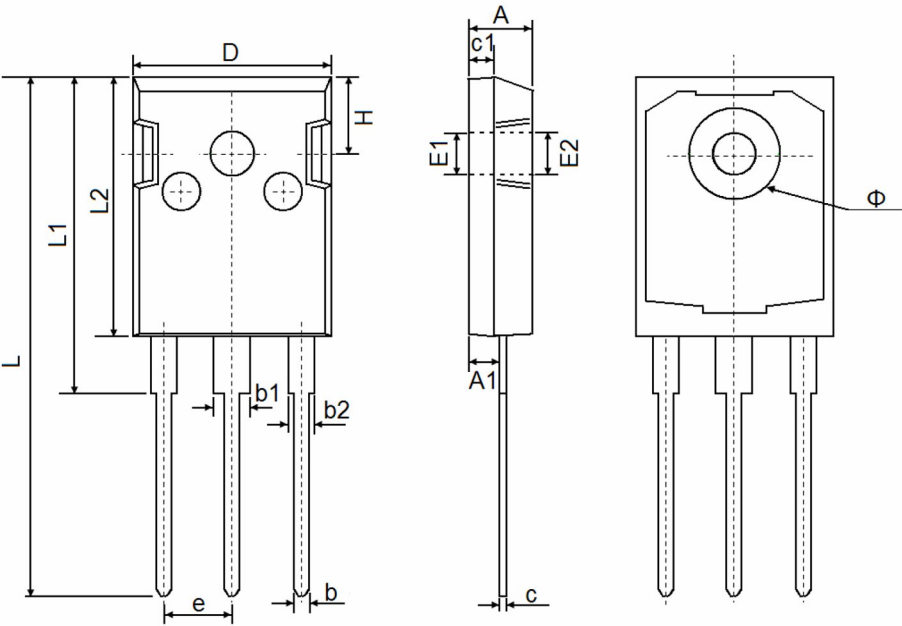
Figure 10 V<sub>GS(th)</sub> vs Junction Temperature



Square Wave Pulse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

# TO-247 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF		0.138 REF	
E2	3.600 REF		0.142 REF	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
Φ	7.100	7.300	0.280	0.287
e	5.450 TYP		0.215 TYP	
H	5.980 REF		0.235 REF	

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